2.5V PHASE LOCKED LOOP DIFFERENTIAL 1:10 SDRAM CLOCK DRIVER

IDTCSPT857/A

FEATURES:

- Optimized for clock distribution in DDR (Double Data Rate) SDRAM applications
- Operating frequency: 60MHz to 200MHz
- Standard speed: PC1600 (DDR200), PC2100 (DDR266)
- A speed: PC1600 (DDR200), PC2100 (DDR266), PC2700 (DDR333)
- 1 to 10 differential clock distribution
- Very low skew (<100ps)
- Very low jitter (<75ps)
- 2.5V AV_{DD} and 2.5V V_{DDQ}
- CMOS control signal input
- Test mode enables buffers while disabling PLL
- Low current power-down mode
- Tolerant of Spread Spectrum input clock
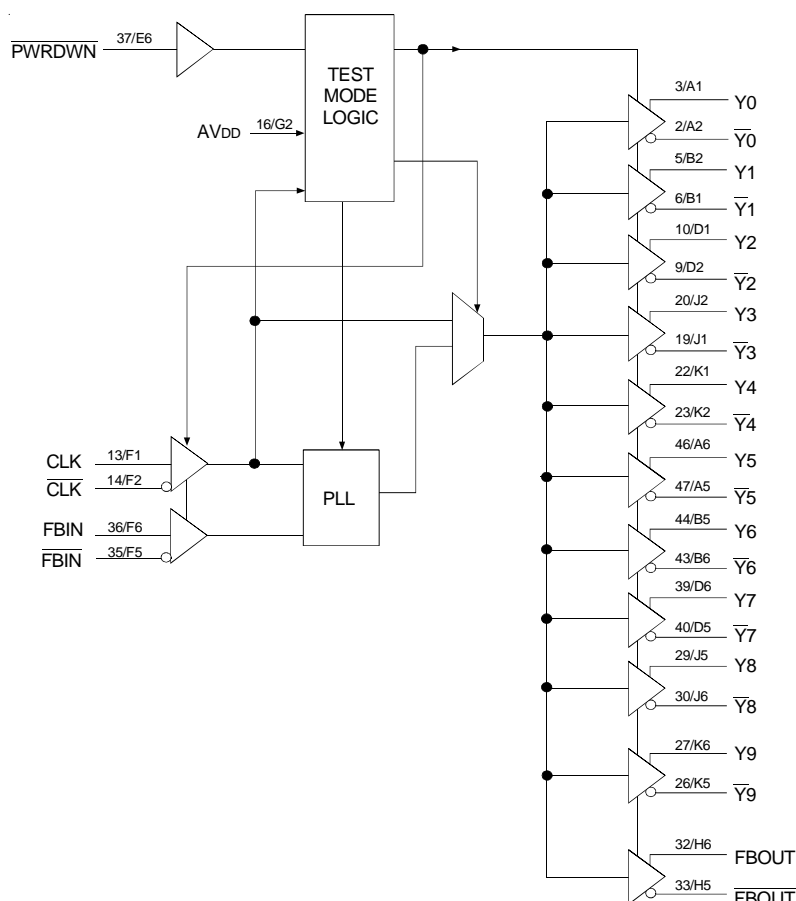- Available in 48-pin TSSOP and 56-pin VFBGA packages

DESCRIPTION:

The CSPT857 is a PLL based clock driver that acts as a zero delay buffer to distribute one differential clock input pair(CLK, $\overline{CLK}$) to 10 differential output pairs (Y[0:9], $\overline{Y}$[0:9]) and one differential pair of feedback clock output (FBOUT, $\overline{FBOUT}$). External feedback pins (FBIN, $\overline{FBIN}$) for synchronization of the outputs to the input reference is provided. A CMOS Enable/Disable pin is available for low power disable. When the output frequency falls below approximately 20MHz, the device will enter power down mode. In this mode, the receivers are disabled, the PLL is turned off, and the output clock drivers are tristated, resulting in a current consumption device of less than 200μA.

The CSPT857 requires no external components and has been optimised for very low I/O phase error, skew, and jitter, while maintaining frequency and duty cycle over the operating voltage and temperature range. The CSPT857, designed for use in both module assemblies and system motherboard based solutions, provides an optimum high-performance clock source.

The CSPT857 is only available in Industrial Temperature Range (-40°C to +85°C), and CSPT857A is only available in Commercial Temperature Range (0°C to +70°C). See Ordering Information for details.

FUNCTIONAL BLOCK DIAGRAM

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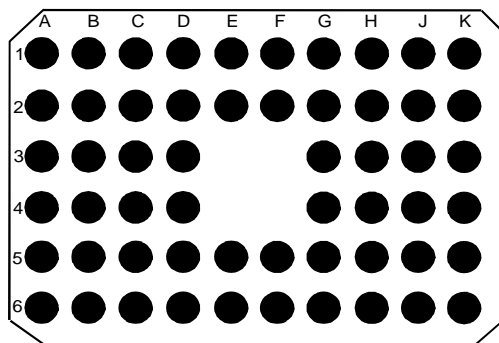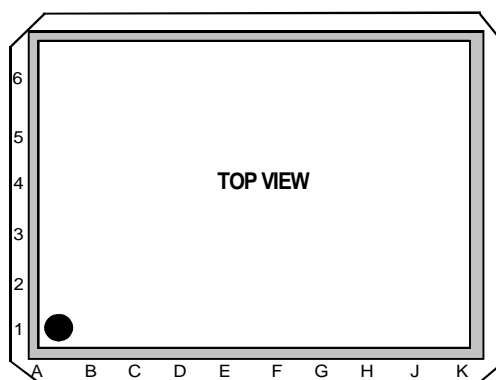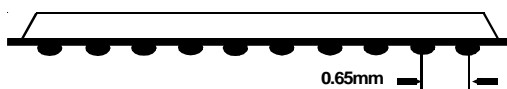
COMMERCIAL AND INDUSTRIAL TEMPERATURE RANGES

OCTOBER 2002

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DSC-5172/8

PIN CONFIGURATIONS

	A	B	C	D	E	F	G	H	J	K
6	Y5	$\overline{Y6}$	GND	Y7	$\overline{\text{PWR DWN}}$	FBIN	VDDQ	FBOUT	$\overline{Y8}$	Y9
5	$\overline{Y5}$	Y6	GND	$\overline{Y7}$	VDDQ	$\overline{\text{FBIN}}$	$\overline{\text{FBOUT}}$	GND	Y8	$\overline{Y9}$
4	GND	VDDQ	NC	NC			NC	NC	VDDQ	GND
3	GND	VDDQ	NC	NC			NC	NC	VDDQ	GND
2	$\overline{Y0}$	Y1	GND	$\overline{Y2}$	VDDQ	$\overline{\text{CLK}}$	AVDD	GND	Y3	$\overline{Y4}$
1	Y0	$\overline{Y1}$	GND	Y2	VDDQ	CLK	VDDQ	AGND	$\overline{Y3}$	Y4

VFBGA
TOP VIEW

56 BALL VFBGA PACKAGE LAYOUT

0.65mm

TOP VIEW

A B C D E F G H J K

PIN CONFIGURATION

GND	1	48	GND
$\overline{Y_0}$	2	47	$\overline{Y_5}$
Y_0	3	46	Y_5
VDDQ	4	45	VDDQ
Y_1	5	44	Y_6
$\overline{Y_1}$	6	43	$\overline{Y_6}$
GND	7	42	GND
GND	8	41	GND
$\overline{Y_2}$	9	40	$\overline{Y_7}$
Y_2	10	39	Y_7
VDDQ	11	38	VDDQ
VDDQ	12	37	$\overline{\text{PWRDWN}}$
CLK	13	36	FBIN
$\overline{\text{CLK}}$	14	35	$\overline{\text{FBIN}}$
VDDQ	15	34	VDDQ
AVDD	16	33	$\overline{\text{FBOUT}}$
AGND	17	32	FBOUT
GND	18	31	GND
$\overline{Y_3}$	19	30	$\overline{Y_8}$
Y_3	20	29	Y_8
VDDQ	21	28	VDDQ
Y_4	22	27	Y_9
$\overline{Y_4}$	23	26	$\overline{Y_9}$
GND	24	25	GND

TSSOP
TOP VIEW

ABSOLUTE MAXIMUM RATINGS[1]

Symbol	Rating	Max	Unit
VDDQ, AVDD	Supply Voltage Range	-0.5 to $+3.6$	V
V_I[2]	Input Voltage Range	-0.5 to VDDQ $+ 0.5$	V
V_O[2]	Voltage range applied to any output in the high or low state	-0.5 to VDDQ $+ 0.5$	V
IIK ($V_I < 0$)	Input Clamp Current	-50	mA
IOK ($V_O < 0$ or $V_O >$ VDDQ)	Output Clamp Current	± 50	mA
IO ($V_O = 0$ to VDDQ)	Continuous Output Current	± 50	mA
VDDQ or GND	Continuous Current	± 100	mA
TSTG	Storage Temperature Range	-65 to $+150$	°C

NOTES:
1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

CAPACITANCE[1]

Parameter	Description	Min.	Typ.	Max.	Unit
CIN	Input Capacitance $V_I =$ VDDQ or GND	2.5	—	3.5	pF
CI(Δ)	Delta Input Capacitance $V_I =$ VDDQ or GND	-0.25	—	0.25	pF
CL	Load Capacitance	—	14	—	pF

NOTE:
1. Unused inputs must be held high or low to prevent them from floating.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	CSPT857			CSPT857A			Unit
		Min.	Typ.	Max.	Min.	Typ.	Max.	
AVDD	Supply Voltage	—	VDDQ	—	VDDQ-0.12	VDDQ	2.7	V
VDDQ	I/O Supply Voltage	2.3	2.5	2.7	2.3	2.5	2.7	V
TA	Operating Free-Air Temperature	-40	—	+85	0	—	+70	°C

PIN DESCRIPTION (TSSOP)

Pin Name	Pin Number	Description
AGND	17	Ground for 2.5V analog supply
AV_{DD}	16	2.5V analog supply
CLK, $\overline{CLK}$	13, 14	Differential clock input
$\overline{FBIN}$, FBIN	35, 36	Feedback differential clock input
FBOUT, $\overline{FBOUT}$	32, 33	Feedback differential clock output
GND	1, 7, 8, 18, 24, 25, 31, 41, 42, 48	Ground
$\overline{PWRDWN}$	37	Output enable for Y and $\overline{Y}$
V_{DDQ}	4, 11, 12, 15, 21, 28, 34, 38, 45	2.5V supply
$Y_{[0:9]}$	3, 5, 10, 20, 22, 27, 29, 39, 44, 46	Buffered output of input clock, CLK
$\overline{Y_{[0:9]}}$	2, 6, 9, 19, 23, 26, 30, 40, 43, 47	Buffered output of input clock, $\overline{CLK}$

PIN DESCRIPTION (VFBGA)

Pin Name	Pin Number	Description
AGND	H1	Ground for 2.5V analog supply
AV_{DD}	G2	2.5V analog supply
CLK, $\overline{CLK}$	F1, F2	Differential clock input
$\overline{FBIN}$, FBIN	F5, F6	Feedback differential clock input
FBOUT, $\overline{FBOUT}$	H6, G5	Feedback differential clock output
GND	A3, A4, C1, C2, C5, C6, H2, H5, K3, K4	Ground
$\overline{PWRDWN}$	E6	Output enable for Y and $\overline{Y}$
V_{DDQ}	B3, B4, E1, E2, E5, G1, G6, J3, J4	2.5V supply
$Y_{[0:9]}$	A1, A6, B2, B5, D1, D6, J2, J5, K1, K6	Buffered output of input clock, CLK
$\overline{Y_{[0:9]}}$	A2, A5, B1, B6, D2, D5, J1, J6, K2, K5	Buffered output of input clock, $\overline{CLK}$

FUNCTION TABLE[1]

INPUTS				OUTPUTS				
AV_{DD}	$\overline{PWRDWN}$	CLK	$\overline{CLK}$	Y	$\overline{Y}$	FBOUT	$\overline{FBOUT}$	PLL
GND	H	L	H	L	H	L	H	Bypassed/OFF
GND	H	H	L	H	L	H	L	Bypassed/OFF
X	L	L	H	Z	Z	Z	Z	OFF
X	L	H	L	Z	Z	Z	Z	OFF
2.5V (nom)	H	L	H	L	H	L	H	ON
2.5V (nom)	H	H	L	H	L	H	L	ON
2.5V (nom)[2]	X	<20MHz	<20MHz	Z	Z	Z	Z	OFF

NOTES:
1. H = HIGH Voltage Level
   L = LOW Voltage Level
   Z = High-Impedance OFF-State
   X = Don't Care

2. Additional feature that senses when the clock input is less than approximately 20MHz and places the part in sleep mode. Reciever inputs and PLL are turned off and outputs = tristate.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Commercial: T_A = 0°C to +70°C; Industrial: T_A = −40°C to +85°C

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{IK}	Input Clamp Voltage (All Inputs)	V_{DDQ} = 2.3V, I_I = -18mA	—	—	− 1.2	V
$V_{IL(dc)}$	Static Input LOW Voltage	$\overline{PWRDWN}$	− 0.3	—	0.7	V
$V_{IH(dc)}$	Static Input HIGH Voltage	$\overline{PWRDWN}$	1.7	—	V_{DDQ} + 0.3	
$V_{IL(ac)}$	Dynamic Input LOW Voltage	CLK, $\overline{CLK}$, FBIN, $\overline{FBIN}$	—	—	0.7	V
$V_{IH(ac)}$	Dynamic Input HIGH Voltage	CLK, $\overline{CLK}$, FBIN, $\overline{FBIN}$	1.7		V_{DDQ}	
V_{OL}	Output LOW Voltage	A_{VDD}/V_{DDQ} = Min., I_{OL} = 100µA	—		0.1	V
		A_{VDD}/V_{DDQ} = Min., I_{OL} = 12mA	—		0.6	
V_{OH}	Output HIGH Voltage	A_{VDD}/V_{DDQ} = Min., I_{OH} = -100µA	V_{DDQ} − 0.1			V
		A_{VDD}/V_{DDQ} = Min., I_{OH} = -12mA	1.7			
V_{IX}	Input Differential Cross Voltage		$V_{DDQ}/2$ − 0.2		$V_{DDQ}/2$ + 0.2	V
$V_{ID(DC)}$ [1]	DC Input Differential Voltage		0.36		V_{DDQ} + 0.6	V
$V_{ID(AC)}$ [1]	AC Input Differential Voltage		0.7		V_{DDQ} + 0.6	V
I_{IN}	Input Current	V_{DDQ} = 2.7V, V_I = 0V to 2.7V			±10	µA
I_{DDPD}	Power-Down Current on V_{DDQ} and A_{VDD}	A_{VDD}/V_{DDQ} = Max., CLK = 0MHz or $\overline{PWRDWN}$ = L	—	100	200	µA
I_{DDQ}	Dynamic Power Supply Current on V_{DDQ}	A_{VDD}/V_{DDQ} = Max., CLK = 200MHz, 120Ω/14pF	—	320	360	mA
		A_{VDD}/V_{DDQ} = Max., CLK = 170MHz, 120Ω/14pF	—	250	300	
I_{ADD}	Dynamic Power Supply Current on A_{VDD}	A_{VDD}/V_{DDQ} = Max., CLK = 170MHz	—		12	mA

NOTE:

1. V_{ID} is the magnitude of the difference between the input level on CLK and the input level on $\overline{CLK}$.

TIMING REQUIREMENTS

Symbol	Parameter	Min.	Max.	Unit
f_{CLK}	Operating Clock Frequency[1,2]	60	200	MHz
	Application Clock Frequency[1,3]	60	200	MHz
t_{DC}	Input Clock Duty Cycle	40	60	%
t_L	Stabilization Time[4]	——	100	μs

NOTES:
1. The PLL will track a spread spectrum clock input.
2. Operating clock frequency is the range over which the PLL will lock, but may not meet all timing specifications.
3. Application clock frequency is the range over which timing specifications apply.
4. Stabilization time is the time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal after power up.

SWITCHING CHARACTERISTICS

Symbol	Description	Test Conditions	CSPT857			CSPT857A			Unit
			Min.	Typ.[1]	Max.	Min.	Typ.[1]	Max.	
t_{PLH}[1]	LOW to HIGH Level Propagation Delay Time	Test mode, CLK to any output		4.5			4.5		ns
t_{PHL}[1]	HIGH to LOW Level Propagation Delay Time	Test mode, CLK to any output		4.5			4.5		ns
$t_{JIT(PER)}$	Jitter (period), see figure 6	66MHz	−90		90	−90		90	ps
		100/ 133/ 167/ 200 MHz	−75		75	−75		75	
$t_{JIT(CC)}$	Jitter (cycle-to-cycle), see figure 3	66MHz	−180		180	−180		180	ps
		100/ 133/ 167/ 200 MHz	−75		75	−75		75	
$t_{JIT(HPER)}$	Half-Period Jitter, see figure 7	66MHz	−160		160	−160		160	ps
		100/ 133/ 167/ 200 MHz	−100		100	−100		100	
$t_{SLR(O)}$	Output Clock Slew Rate (Single-Ended)	100/ 133/ 167/ 200 MHz (20% to 80%)	1		2	1		2	V/ns
$t_{SLR(I)}$	Input Clock Slew Rate		1		4	1		4	V/ns
$t(\varnothing)$	Static Phase Offset, see figure 4[2,3]	66/ 100/ 133/ 167/ 200 MHz	−100		100	−50		50	ps
$t_{SK(O)}$	Output Skew, see figure 5				75			75	ps
t_R, t_F	Output Rise and Fall Times (20% to 80%)	Load: 120Ω / 14pF	650		900	650		900	ps
V_{OX}[5]	Output Differential Voltage	Differential outputs are terminated with 120Ω	$V_{DDQ}/2$ −0.2		$V_{DDQ}/2$ +0.2	$V_{DDQ}/2$ −0.15		$V_{DDQ}/2$ +0.15	V
The PLL on the CSPT857 will meet all the above test parameters while supporting SSC synthesizers[4] with the following parameters:									
SSC	Modulation Frequency	—	30	—	50	30	—	50	KHz
SSC	Clock Input Frequency Deviation	—	0	—	-0.5	0	—	-0.5	%
f_{3dB}	PLL Loop Bandwidth	—	—	5	—	—	5	—	MHz

NOTES:
1. Refers to transition of non-inverting output.
2. Static phase offset does not include jitter.
3. $t(\phi)$ is measured with input clock slew rate $t_{SLR(I)}$ = 2V/ns and an input differential voltage V_{ID} of 1.75V.
4. The SSC requirements meet the Intel PC100 SDRAM Registered DIMM specification.
5. V_{OX} is specified at the SDRAM clock input or test load.
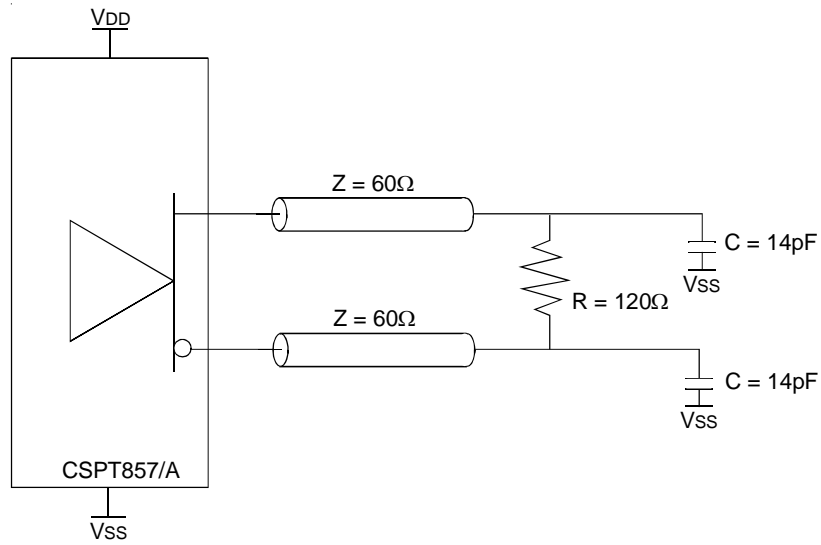
TEST CIRCUIT AND SWITCHING WAVEFORMS
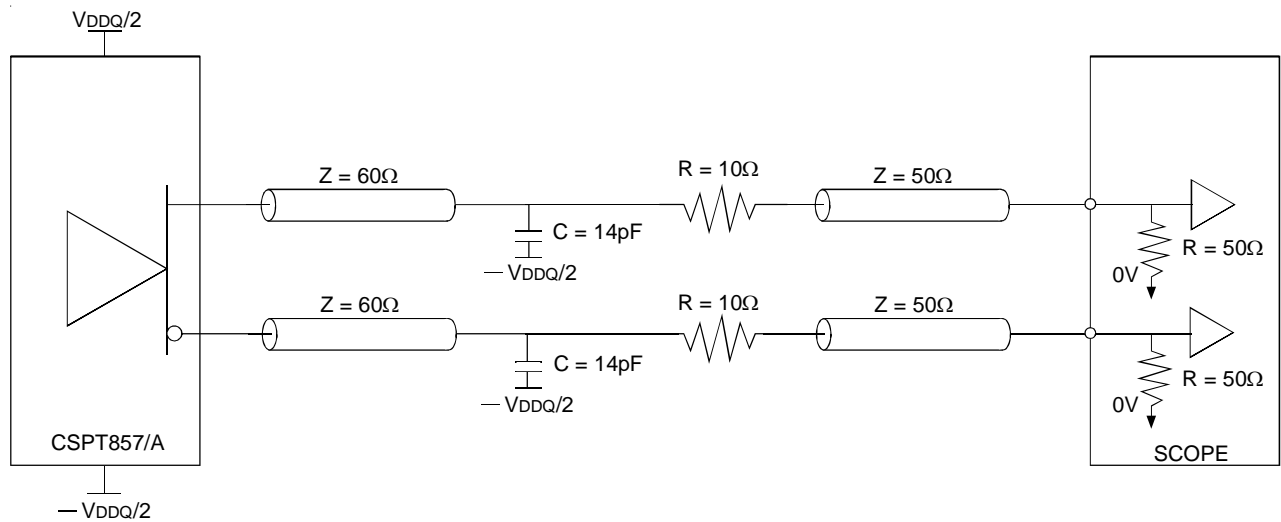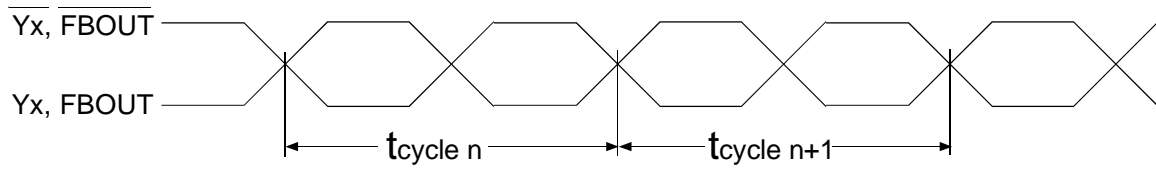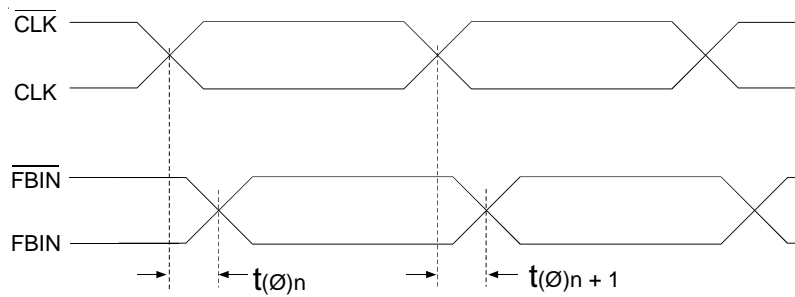
Figure 1. Output Load

Figure 2. Output Load Test Circuit

TEST CIRCUIT AND SWITCHING WAVEFORMS

$$t_{jit(cc)} = t_{cycle\ n} - t_{cycle\ n+1}$$

Figure 3. Cycle-to-Cycle jitter

$$t_{(\varnothing)} = \frac{\sum_{1}^{n\ =\ N} t_{(\varnothing)n}}{N}$$

(N is a large number of samples)
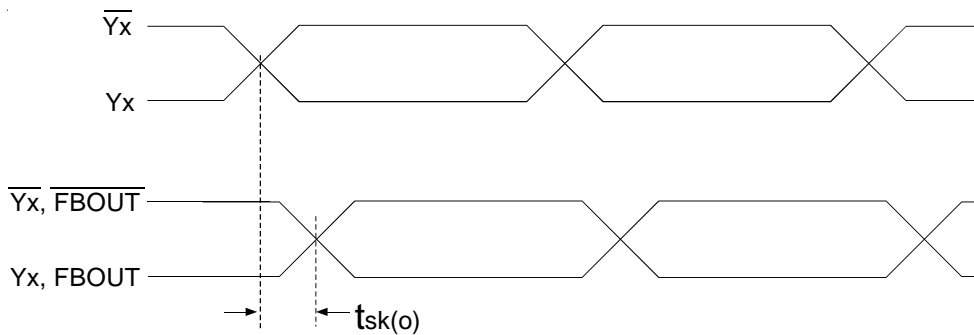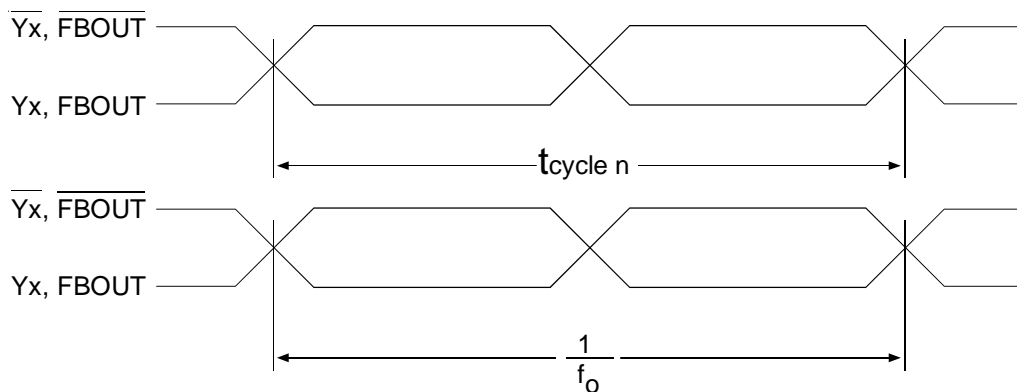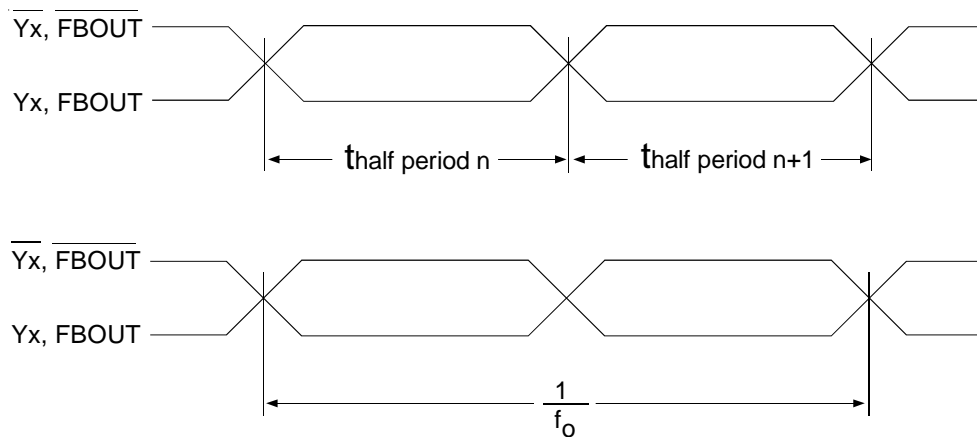
Figure 4. Static Phase Offset

Figure 5. Output Skew

TEST CIRCUIT AND SWITCHING WAVEFORMS

$\overline{Yx}$, $\overline{FBOUT}$

Yx, FBOUT

$t_{cycle\ n}$

$\overline{Yx}$, $\overline{FBOUT}$

Yx, FBOUT

$\dfrac{1}{f_O}$

$$t_{jit(per)} = t_{cycle\ n} - \dfrac{1}{f_O}$$

Figure 6. Period jitter

$\overline{Yx}$, $\overline{FBOUT}$

Yx, FBOUT

$t_{half\ period\ n}$ $t_{half\ period\ n+1}$

$\overline{Yx}$, $\overline{FBOUT}$

Yx, FBOUT

$\dfrac{1}{f_O}$

$$t_{jit(hper)} = t_{half\ period\ n} - \dfrac{1}{2*f_O}$$

Figure 7. Half-Period jitter

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TEST CIRCUIT AND SWITCHING WAVEFORMS

Clock Inputs and Outputs

80%

20%

t_R

80%

20%

t_F

V_{ID}, V_{OD}

Figure 8. Input and Output Slew Rates

APPLICATION INFORMATION

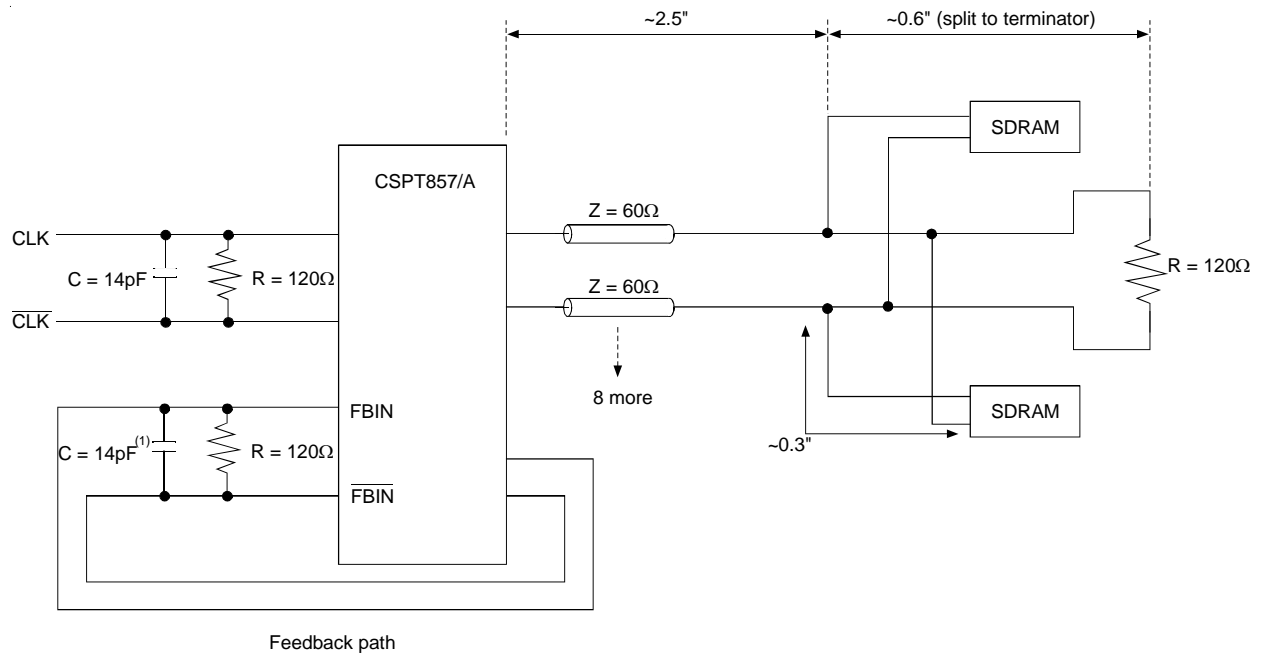| Clock Structure	# of SDRAM Loads per Clock	Clock Loading on the PLL outputs (pF)	
		Min.	Max.
#1	2	4	7
#2	4	8	14

APPLICATION INFORMATION
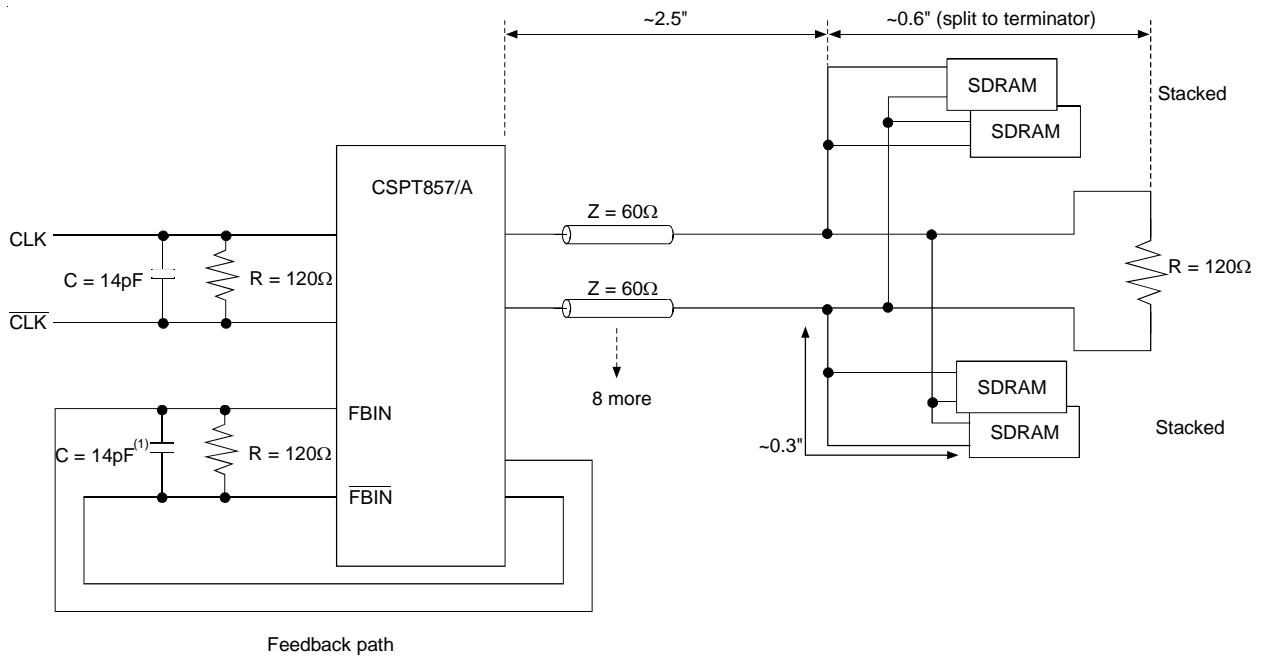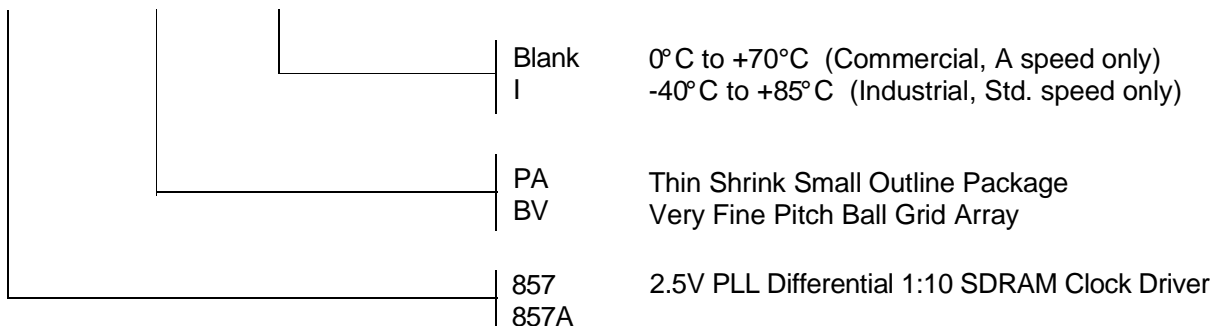
Figure 9. Clock Structure 1

Figure 10. Clock Structure 2

NOTE:
1.   Memory module vendors may need to adjust the feedback capacitive load in order to meet DDR SDRAM registered DIMM timing requirements.

ORDERING INFORMATION

```
IDTCSPT   XXXXX      XX      X
          Device Type   Package   Process
```

Blank	0°C to +70°C	(Commercial, A speed only)
I	-40°C to +85°C	(Industrial, Std. speed only)

PA	Thin Shrink Small Outline Package
BV	Very Fine Pitch Ball Grid Array

857	2.5V PLL Differential 1:10 SDRAM Clock Driver
857A	

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